2SB1398

Silicon PNP epitaxial planar type

For low-frequency power amplification

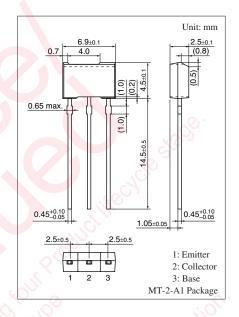
■ Features

- Low collector-emitter saturation voltage V_{CE(sat)}
- Large collector current I_C
- Allowing supply with the radial taping

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	-30	V	
Collector-emitter voltage (Base open)	V_{CEO}	-25	V	
Emitter-base voltage (Collector open)	V_{EBO}	-7	V	
Collector current	I_{C}	-5	A	
Peak collector current	I_{CP}	-8	A	
Collector power dissipation *	P_{C}	1	W	
Junction temperature	T_{j}	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

Note) *: Print circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion



■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = -1 \text{ mA}, I_B = 0$	-25	95		V
Emitter-base voltage (Collector open)	$V_{\rm EBO}$	$I_E = -10 \mu\text{A}, I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -10 \text{ V}, I_E = 0$	7.7		-100	nA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = -5 \text{ V}, I_C = 0$			-100	nA
Forward current transfer ratio *1, 2	h _{FE}	$V_{CE} = -2 \text{ V}, I_{C} = -2 \text{ A}$	90		205	_
Collector-emitter saturation voltage *1	V _{CE(sat)}	$I_C = -3 \text{ A}, I_B = -0.1 \text{ A}$			-1	V
Transition frequency	f_T	$V_{CB} = -6 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		120		MHz
Collector output capacitance	C _{ob}	$V_{CB} = -20 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$			85	pF
(Common base, input open circuited)		SO 70.				

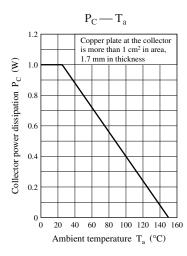
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

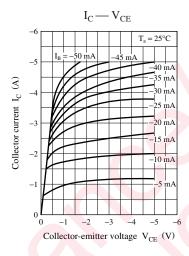
2. *1: Pulse measurement

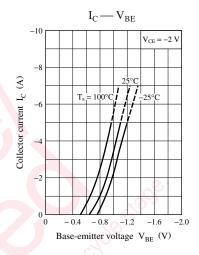
*2: Rank classification

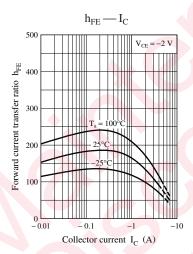
Rank	Р	Q
h_{FE}	90 to 135	120 to 205

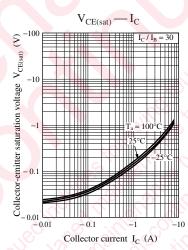
Panasonic

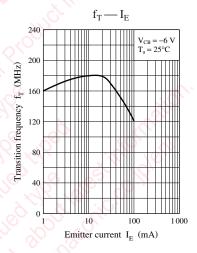


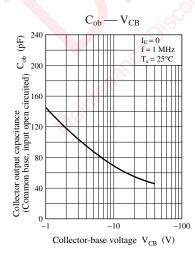












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